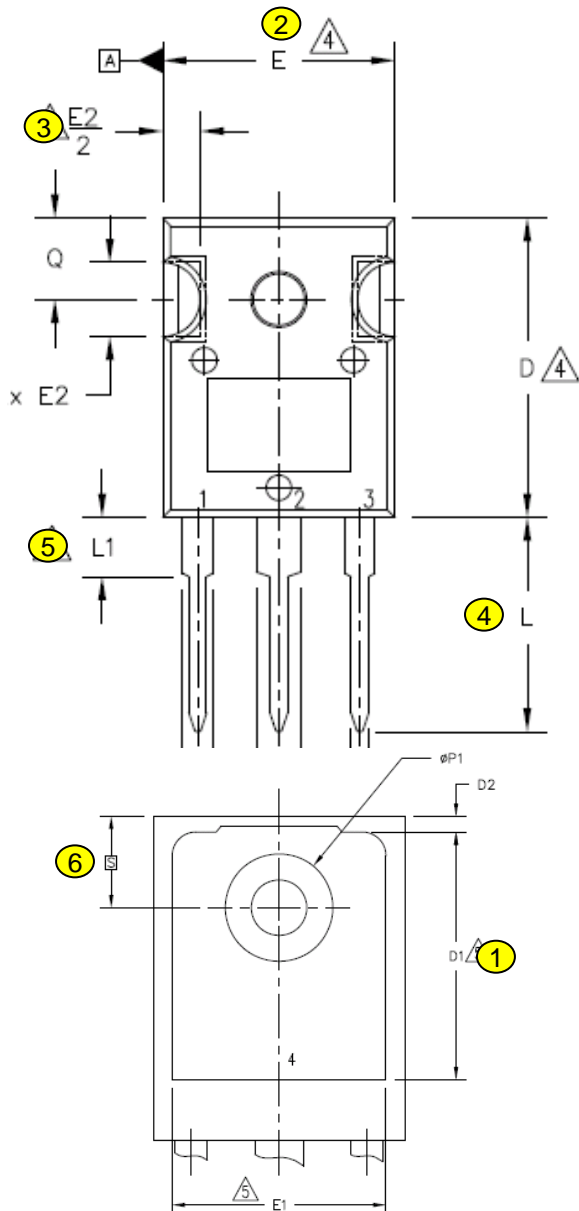


# TO-247 POD: IRMX vs New Leadframe



Symbol	IR POD	Subcon X POD	Subcon X MIN	Subcon X MAX	REMARK
A	4.65~5.31	4.83~5.2	4.83	5.20	
A1	2.21~2.59	2.29~2.54	2.29	2.54	
A2	1.5~2.49	1.91~2.16	1.91	2.16	
b	0.99~1.40	1.07~1.33	1.07	1.33	
b2	1.65~2.39	1.91~2.41	1.91	2.41	
b4	2.59~3.43	2.87~3.38	2.87	3.38	
c	0.38~0.89	0.55~0.68	0.55	0.68	
D	19.71~20.70	20.8~ <b>21.1</b>	20.80	21.10	New LF package is taller
① D1	13.08 Min	16.25~17.65	16.25	17.65	
② E	15.29~15.87	15.75~ <b>16.13</b>	15.75	16.13	New LF package is wider
E1	13.46 Min	13.0~14.5	13.00	14.50	
③ E2	4.52~5.49	<b>3.68</b> ~5.0	3.68	5.00	
e	5.46 Typ	5.45 Typ	5.45		
④ L	14.2~16.1	19.8~ <b>20.32</b>	19.80	20.32	New LF overall lead length is longer
⑤ L1	3.71~4.29	4.10~ <b>4.40</b>	4.10	4.40	New LF stand off is longer
φ P	3.56~3.66	3.51~3.65	3.51	3.65	
⑥ Q	5.31~5.69	5.49~6.00	5.49	6.00	
S	5.51 Typ	<b>6.04~6.30</b>	6.04	6.30	New LF center of mounting hole farther from top edge of package

Note New LF min/max is measured actual package dimension

Subcon X TO-247 is not a drop-in replacement for IRMX parts.

L1 is critical because this is the seating plane of the device when mounted on PCB. If device is mounted with heat sink then the mounting hole of device will not be aligned to the heat sink mounting screw.